

High and Low Side Driver

Features

- Floating channel designed for bootstrap operation
- Fully operational to +600V
- Tolerant to negative transient voltage
- dV/dt immune
- Gate drive supply range from 10 to 20V
- Undervoltage lockout for both channels
- 3.3V logic compatible
- Separate logic supply range from 3.3V to 20V
- Logic and power ground ± 5 V offset
- CMOS Schmitt-triggered inputs with pull-down
- Cycle by cycle edge-triggered shutdown logic
- Matched propagation delay for both channels
- Outputs in phase with inputs

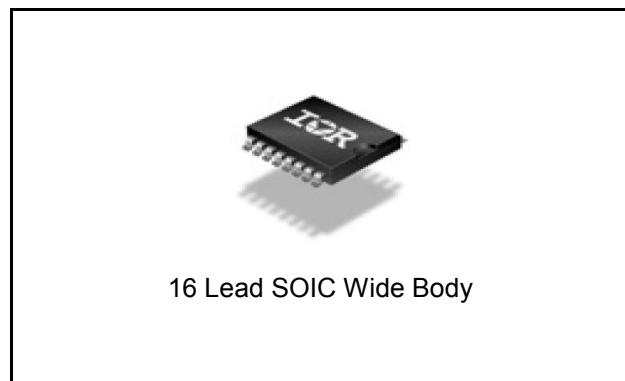
Product Summary

V _{OFFSET}	600V max.
I _{O+/-}	2A / 2A
V _{OUT}	10 – 20V
Ton/off (typ.)	120 & 94 ns
Delay Matching (typ.)	20 ns

Description

The IR25607 is a high voltage, high speed power MOSFET and IGBT driver with independent high and low side referenced output channels. Proprietary HVIC and latch immune CMOS technologies enable ruggedized monolithic construction. Logic inputs are compatible with standard CMOS or LSTTL output, down to 3.3V logic. The output drivers feature a high pulse current buffer stage designed for minimum driver cross-conduction. Propagation delays are matched to simplify use in high frequency applications. The floating channel can be used to drive an N-channel power MOSFET or IGBT in the high side configuration which operates up to 600 V.

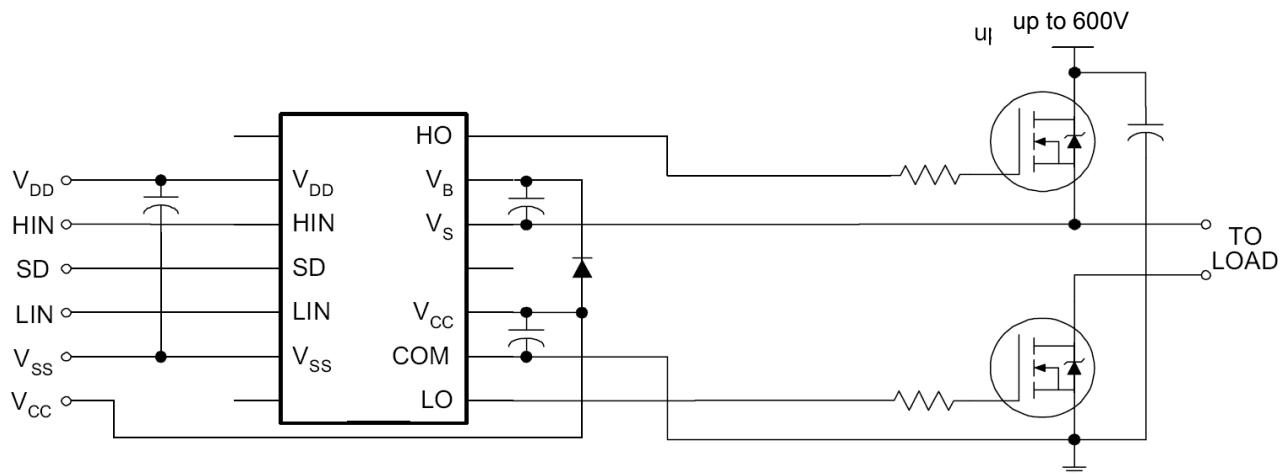
Package Options



Ordering Information

Base Part Number	Package Type	Standard Pack		Orderable Part Number
		Form	Quantity	
IR25607SPBF	SO16W	Tube	45	IR25607SPBF
IR25607SPBF	SO16W	Tape and Reel	1000	IR25607STRPBF

Typical Connection Diagram



(Refer to Lead Assignments for correct pin configuration). This/These diagram(s) show electrical connections only. Please refer to our Application Notes and DesignTips for proper circuit board layout.

Absolute Maximum Ratings

Absolute maximum ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions.

Symbol	Definition	Min.	Max.	Units
V_B	High side floating supply voltage	-0.3	625	V
V_S	High side floating supply offset voltage	$V_B - 25$	$V_B + 0.3$	
V_{HO}	High side floating output voltage	$V_S - 0.3$	$V_B + 0.3$	
V_{CC}	Low side and logic fixed supply voltage	-0.3	25	
V_{LO}	Low side output voltage	-0.3	$V_{CC} + 0.3$	
V_{DD}	Logic supply voltage	-0.3	$V_{SS} + 25$	
V_{SS}	Logic supply offset voltage	$V_{CC} - 25$	$V_{CC} + 0.3$	
V_{IN}	Logic input voltage (HIN, LIN & SD)	$V_{SS} - 0.3$	$V_{DD} + 0.3$	
dV_s/dt	Allowable offset supply voltage transient	—	50	V/ns
P_D	Package power dissipation @ $T_A \leq +25^\circ\text{C}$	—	1.25	W
R_{thJA}	Thermal resistance, junction to ambient	—	100	$^\circ\text{C}/\text{W}$
T_J	Junction temperature	—	150	$^\circ\text{C}$
T_S	Storage temperature	-55	150	
T_L	Lead temperature (soldering, 10 seconds)	—	300	

Recommended Operating Conditions

For proper operation the device should be used within the recommended conditions. The V_S and V_{SS} offset ratings are tested with all supplies biased at 15V differential.

Symbol	Definition	Min.	Max.	Units
V_B	High side floating supply absolute voltage	$V_S + 10$	$V_S + 20$	V
V_S	High side floating supply offset voltage	†	600	
V_{HO}	High side floating output voltage	V_S	V_B	
V_{CC}	Low side fixed supply voltage	10	20	
V_{LO}	Low side output voltage	0	V_{CC}	
V_{DD}	Logic supply voltage	$V_{SS} + 3$	$V_{SS} + 20$	
V_{SS}	Logic supply offset voltage	-5 ††	5	
V_{IN}	Logic input voltage (HIN, LIN & SD)	V_{SS}	V_{DD}	
T_A	Ambient temperature	-40	125	$^\circ\text{C}$

† Logic operational for V_S of -5 to +600V. Logic state held for V_S of -5V to - V_{BS} . (Please refer to Design Tip DT97-3 for more details).

†† When $V_{DD} < 5\text{V}$, the minimum V_{SS} offset is limited to $-V_{DD}$.

Dynamic Electrical Characteristics

V_{BIAS} (V_{CC} , V_{BS} , V_{DD}) = 15V, $CL = 1000 \text{ pF}$, $V_{SS} = \text{COM}$ and $T_A = 25^\circ\text{C}$ unless otherwise specified.

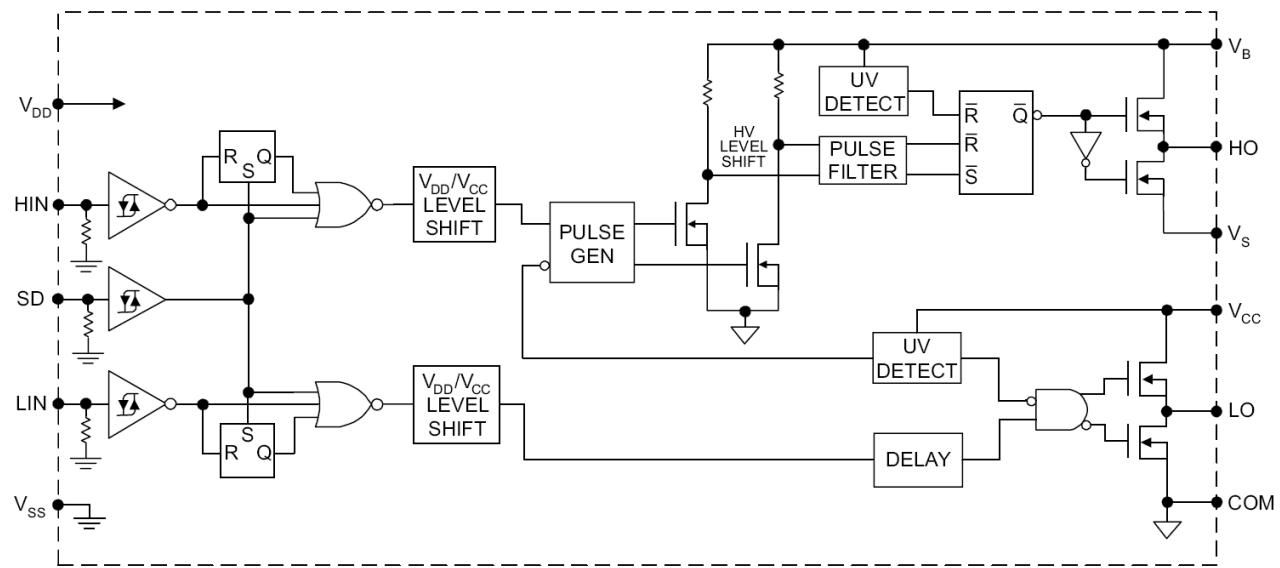
Symbol	Definition	Min.	Typ.	Max.	Units	Test Conditions
ton	Turn-on propagation delay	—	120	150	ns	$V_S = 0V$
toff	Turn-off propagation delay	—	94	125		$V_S = 600V$
tsd	Shutdown propagation delay	—	110	140		$V_S = 600V$
tr	Turn-on rise time	—	25	35		
tf	Turn-off fall time	—	17	25		
MT	Delay matching, HS & LS turn-on/off	—	—	20		

Static Electrical Characteristics

V_{BIAS} (V_{CC} , V_{BS} , V_{DD}) = 15V, $V_{SS} = \text{COM}$ and $T_A = 25^\circ\text{C}$ unless otherwise specified. The V_{IN} , V_{TH} and I_{IN} parameters are referenced to V_{SS} and are applicable to all three logic input leads: HIN, LIN and SD. The V_O and I_O parameters are referenced to COM and are applicable to the respective output leads: HO and LO.

Symbol	Definition	Min.	Typ.	Max.	Units	Test Conditions
V_{IH}	Logic “1” input voltage	9.5	—	—	V	
V_{IL}	Logic “0” input voltage	—	—	6.0		
V_{OH}	High level output voltage, $V_{BIAS} - V_O$	—	—	1.2		$I_O = 0A$
V_{OL}	Low level output voltage, V_O	—	—	0.1		$I_O = 0A$
I_{LK}	Offset supply leakage current	—	—	50		$V_B = V_S = 600V$
I_{QBS}	Quiescent V_{BS} supply current	—	125	230		$V_{IN} = 0V$ or V_{DD}
I_{QCC}	Quiescent V_{CC} supply current	—	180	340	μA	$V_{IN} = 0V$ or V_{DD}
I_{QDD}	Quiescent V_{CC} supply current	—	15	30		$V_{IN} = 0V$ or V_{DD}
I_{IN+}	Logic “1” input bias current	—	20	40		$V_{IN} = V_{DD}$
I_{IN-}	Logic “0” input bias current	—	—	1		$V_{IN} = 0V$
V_{BSUV+}	V_{BS} supply undervoltage positive going threshold	7.5	8.6	9.7	V	
V_{BSUV-}	V_{BS} supply undervoltage negative going threshold	7.0	8.2	9.4		
V_{CCUV+}	V_{CC} supply undervoltage positive going threshold	7.4	8.5	9.6		
V_{CCUV-}	V_{CC} supply undervoltage negative going threshold	7.0	8.2	9.4		
I_{O+}	Output high short circuit pulsed current	2	2.5	—	A	$V_O = 0V$, $V_{IN} = V_{DD}$ $PW \leq 10 \mu s$
I_{O-}	Output low short circuit pulsed current	2	2.5	—		$V_O = 15V$, $V_{IN} = V_{DD}$ $PW \leq 10 \mu s$

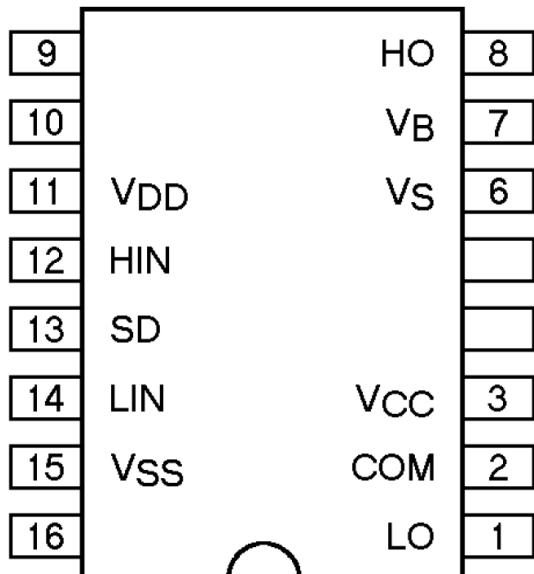
Functional Block Diagram



Lead Definitions

Symbol	Description
V _{DD}	Logic supply
HIN	Logic input for high side gate driver output (HO), in phase
SD	Logic input for shutdown
LIN	Logic input for low side gate driver output (LO), in phase
V _{SS}	Logic ground
V _B	High side floating supply
HO	High side gate drive output
V _S	High side floating supply return
V _{CC}	Low side and logic fixed supply
LO	Low side gate drive output
COM	Low side return

Lead Assignments



Application Information and Additional Details

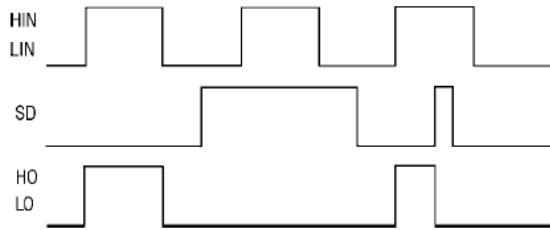


Figure 1. Input/Output Timing Diagram

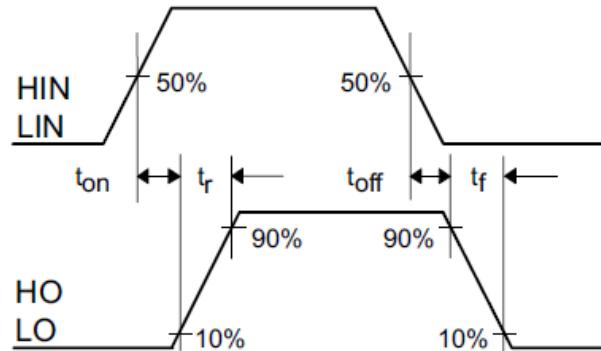


Figure 2. Switching Time Waveform Definitions

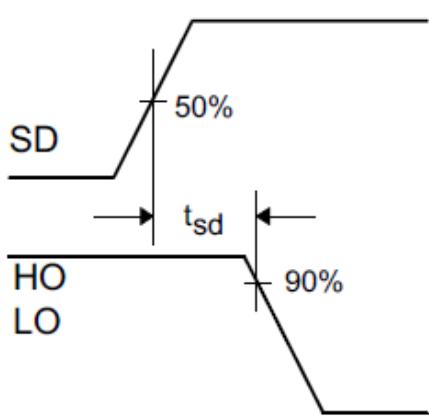


Figure 3. Shutdown Waveform Definitions

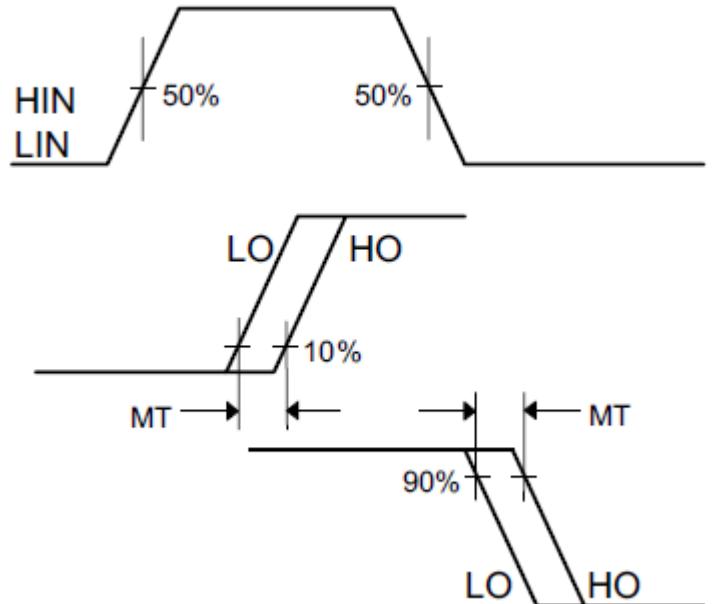


Figure 4. Delay matching Waveform Definitions

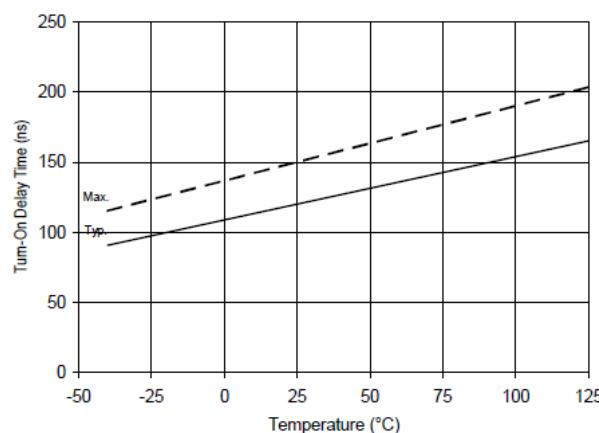


Figure 5A. Turn On Time vs. Temperature

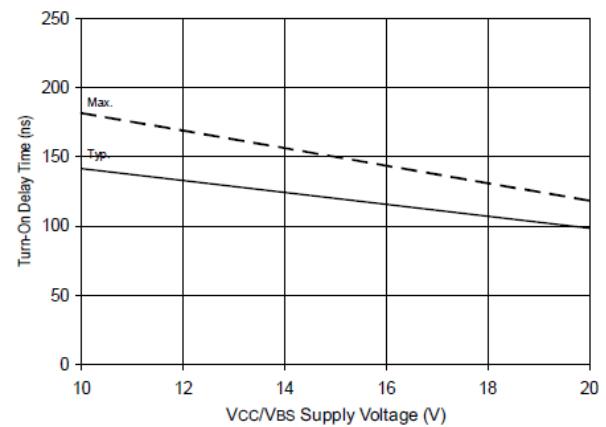


Figure 5B. Turn On Time vs. V_{CC}/V_{BS} Supply Voltage

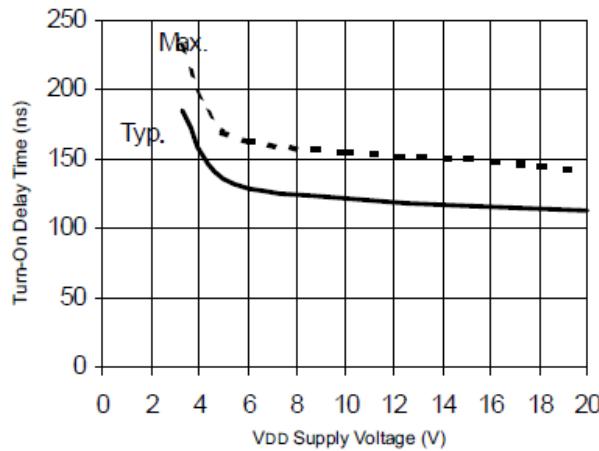


Figure 5C. Turn On Time vs. V_{DD} Supply Voltage

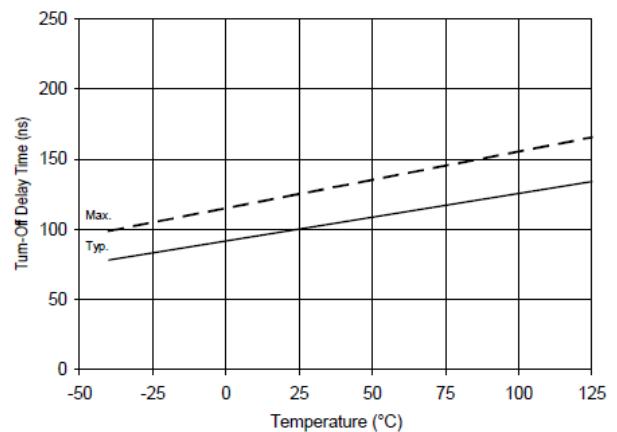


Figure 6A. Turn Off Time vs. Temperature

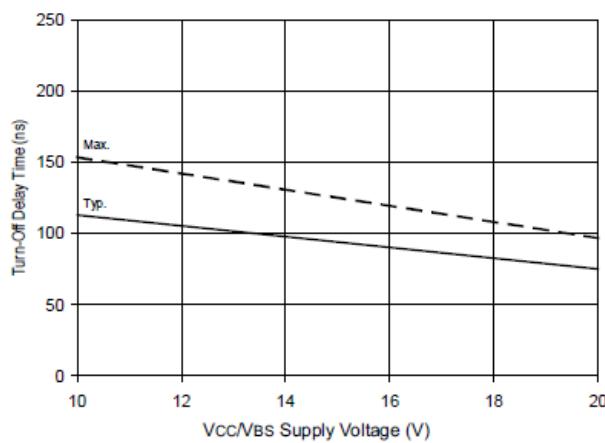


Figure 6B. Turn Off Time vs. V_{CC}/V_{BS} Supply Voltage

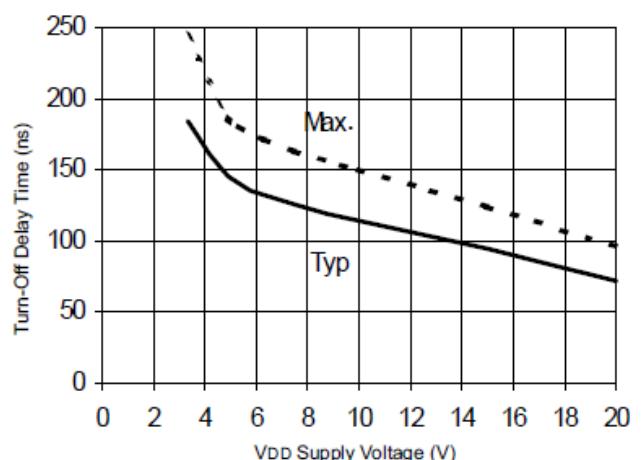


Figure 6C. Turn Off Time vs. V_{DD} Supply Voltage

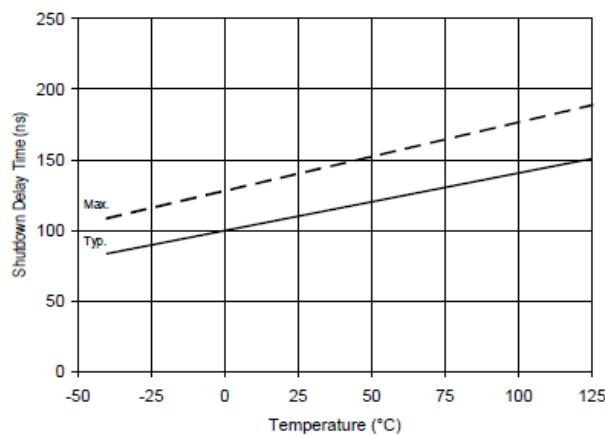


Figure 7A. Shutdown Time vs. Temperature

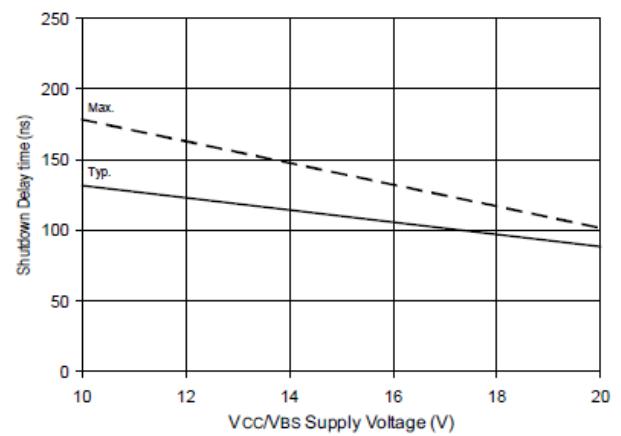
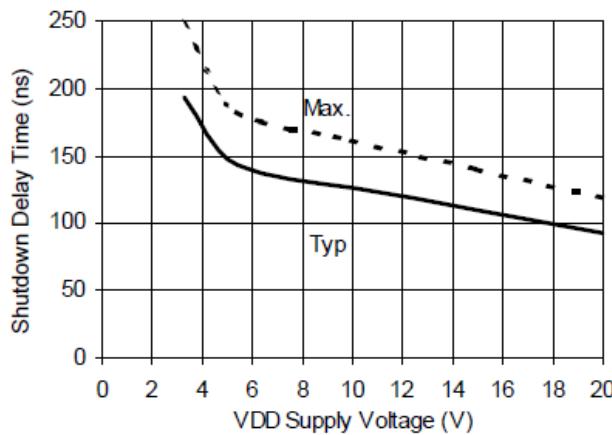
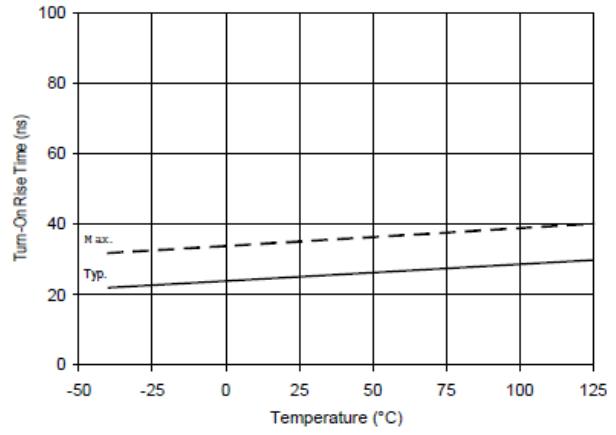
Figure 7B. Shutdown Time vs. V_{CC}/V_{BS} Supply VoltageFigure 7C. Shutdown Time vs. V_{DD} Supply Voltage

Figure 8A. Turn On Rise Time vs. Temperature

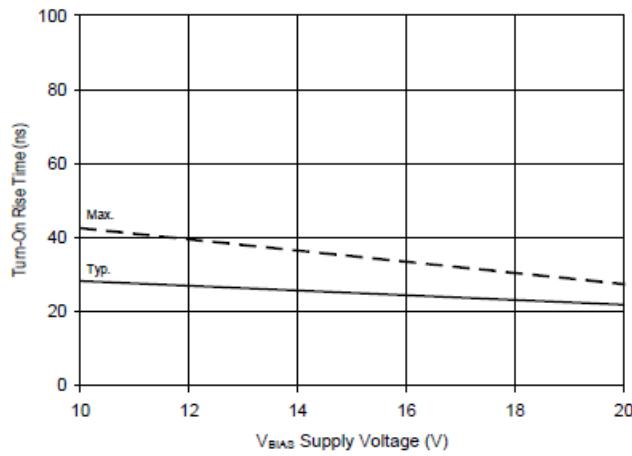


Figure 8B. Turn On Rise Time vs. Voltage

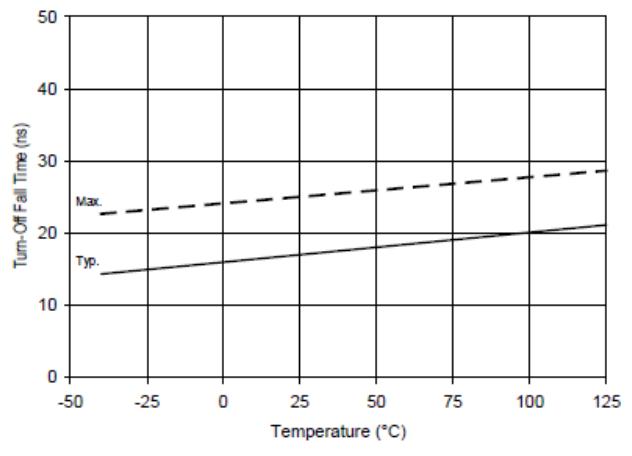


Figure 9A. Turn Off Fall Time vs. Temperature

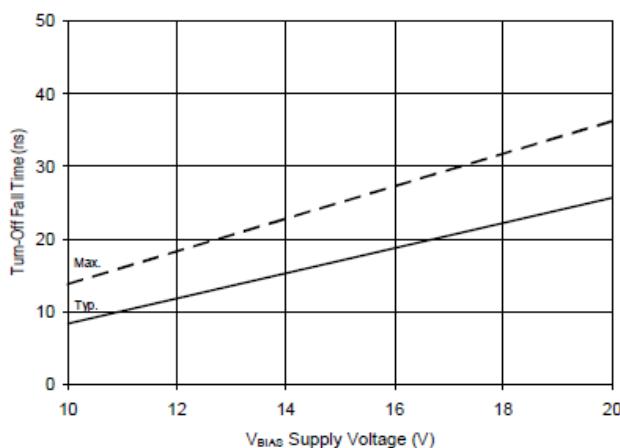


Figure 9B. Turn Off Fall Time vs. Voltage

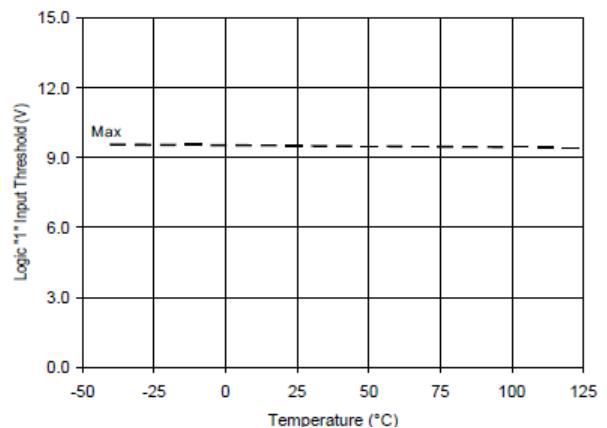


Figure 10A. logic '1' Input Threshold vs. Temperature

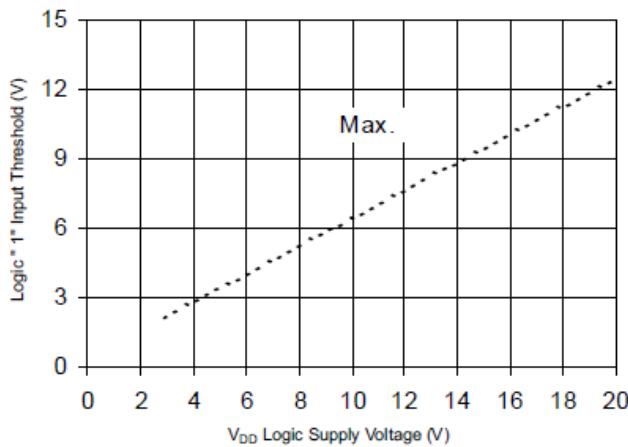


Figure 10B. Logic '1' Input Threshold vs. Voltage

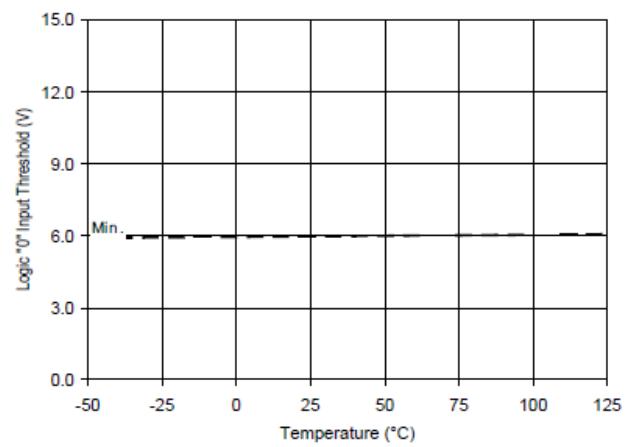


Figure 11A. Logic '0' Input Threshold vs. Temperature

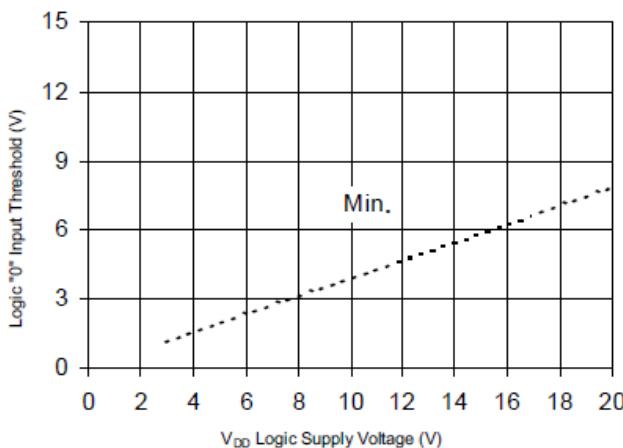


Figure 11B. Logic '0' Input Threshold vs. Voltage

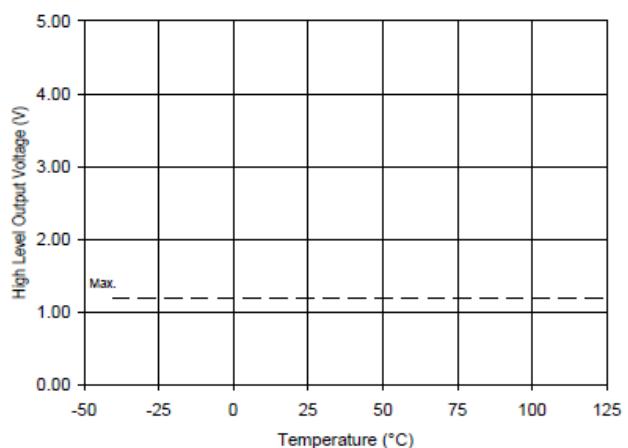


Figure 12A. High Level Output vs. Temperature

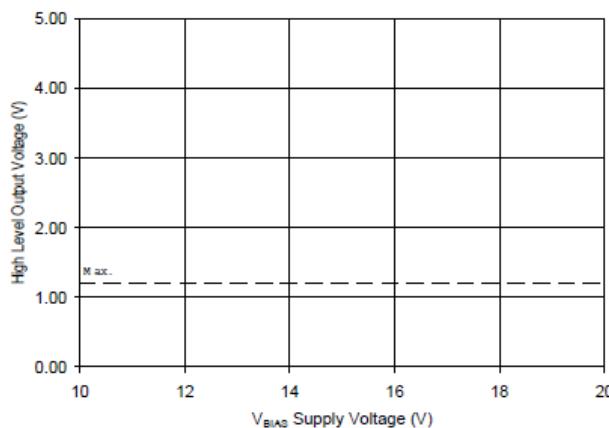


Figure 12B. High Level Output vs. Voltage

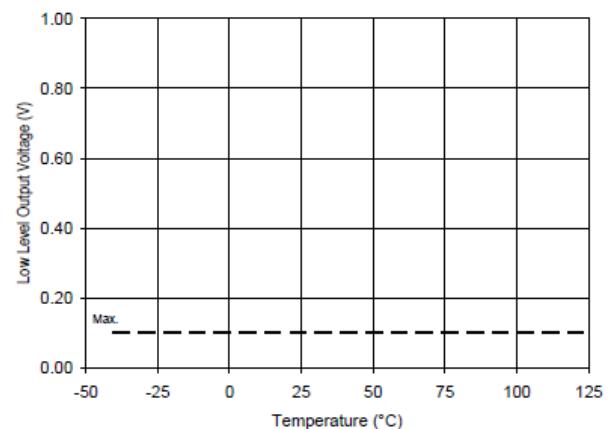


Figure 13A. Low Level Output vs. Temperature

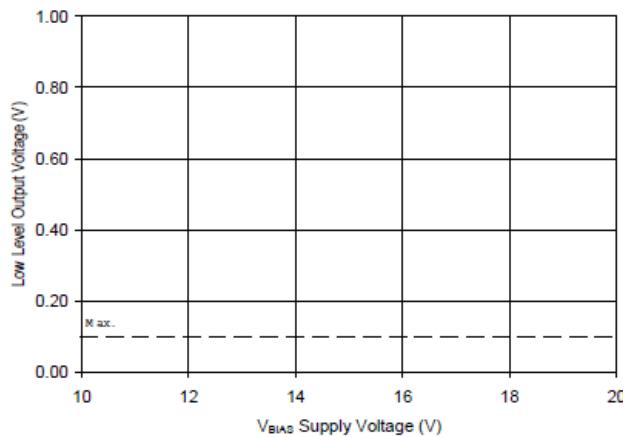


Figure 13B. Low Level Output vs. Voltage

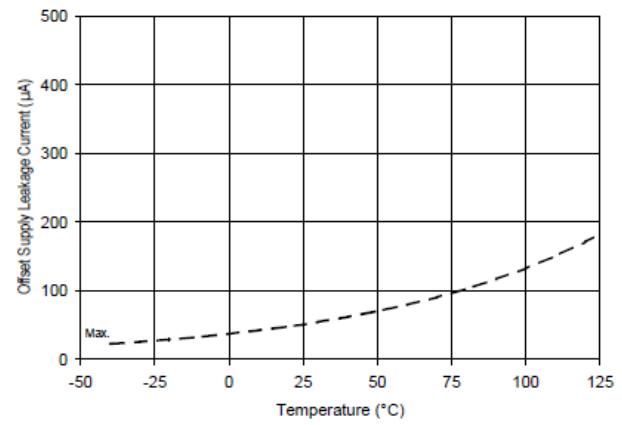


Figure 14A. Offset Supply Current vs. Temperature

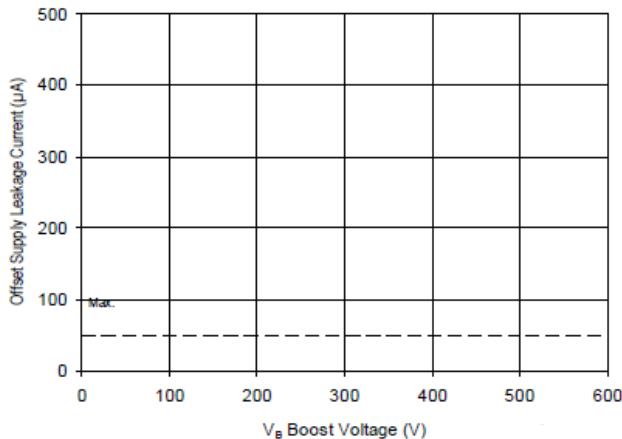


Figure 14B. Offset Supply Current vs. Voltage

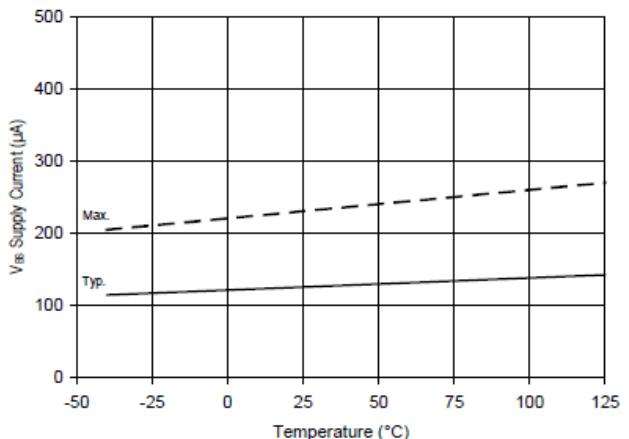


Figure 15A. V_{BS} Supply Current vs. Temperature

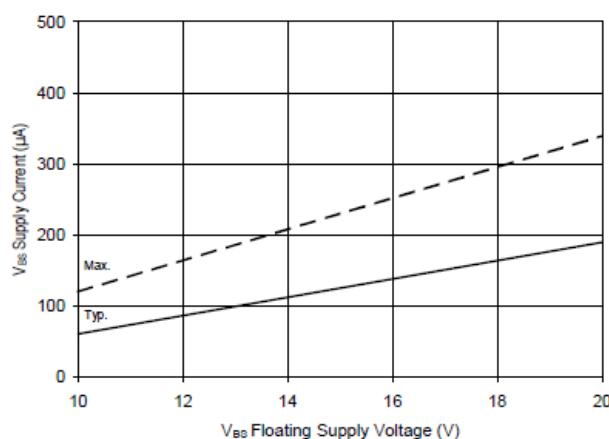
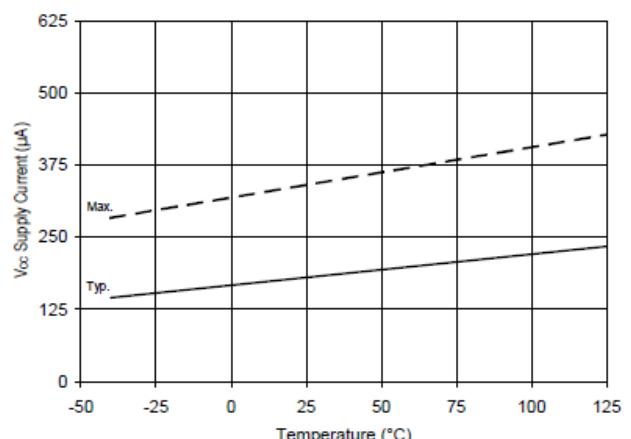
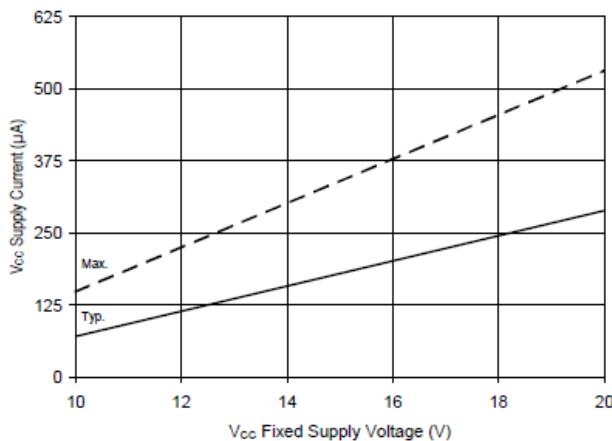
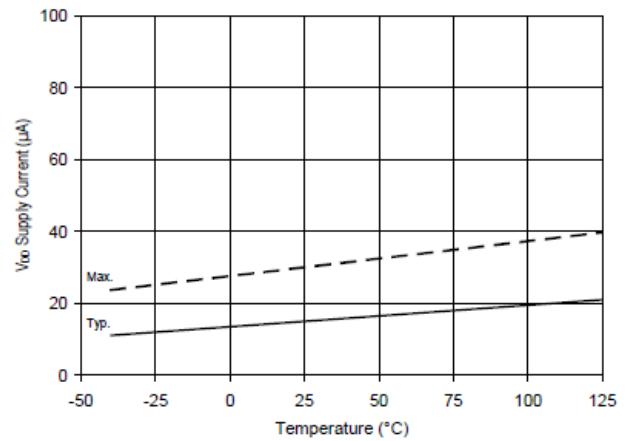
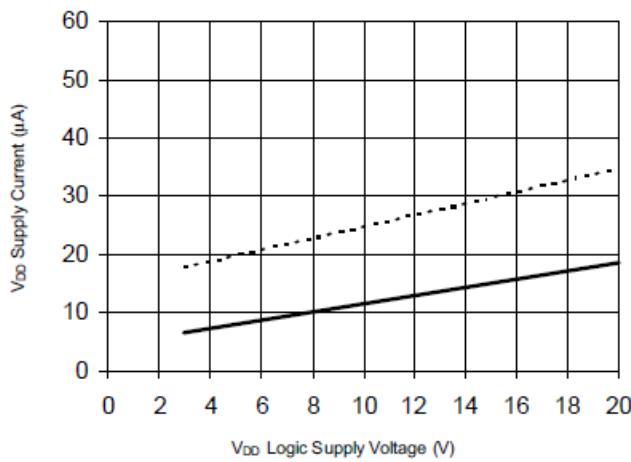
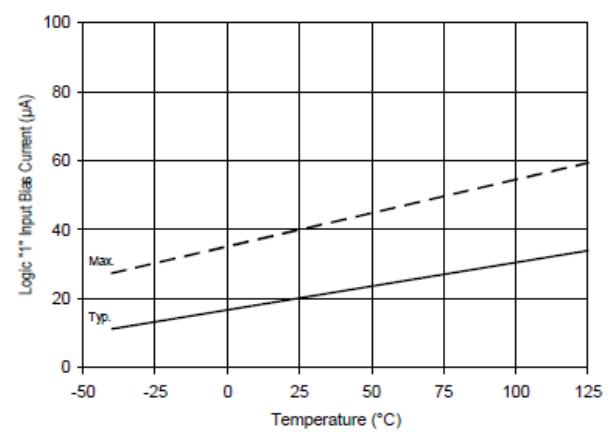
Figure 15B. V_{Bs} Supply Current vs. VoltageFigure 16A. V_{CC} Supply Current vs. TemperatureFigure 16B. V_{CC} Supply Current vs. VoltageFigure 17A. V_{DD} Supply Current vs. TemperatureFigure 17B. V_{DD} Supply Current vs. V_{DD} Voltage

Figure 18A. Logic '1' Input Current vs. Temperature

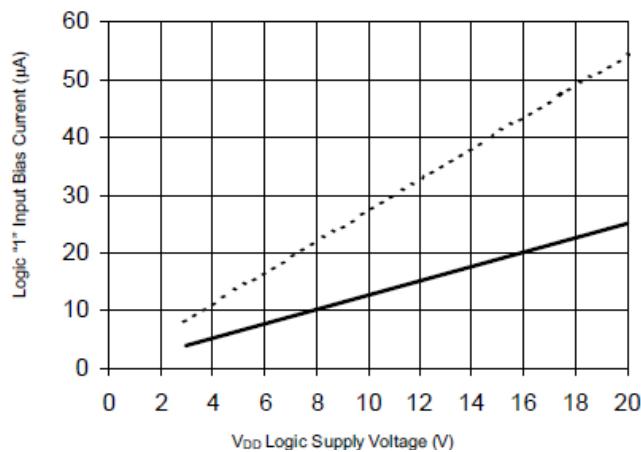
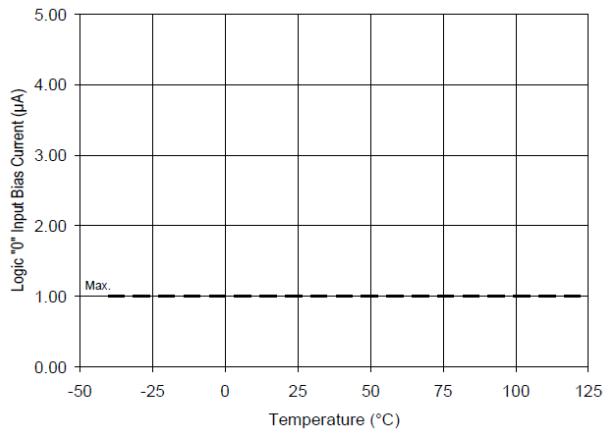
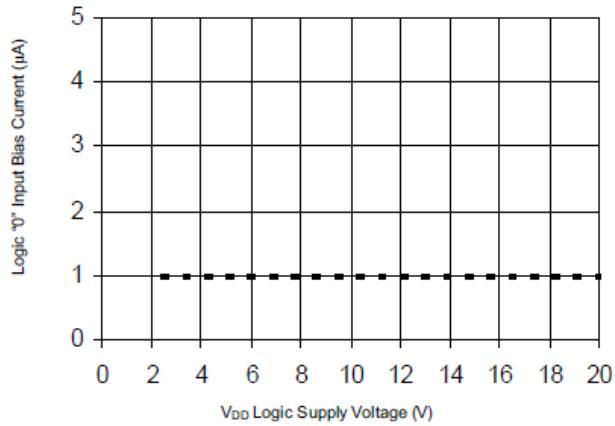
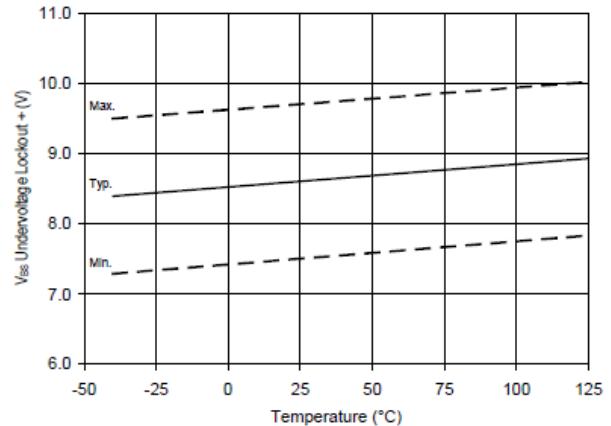
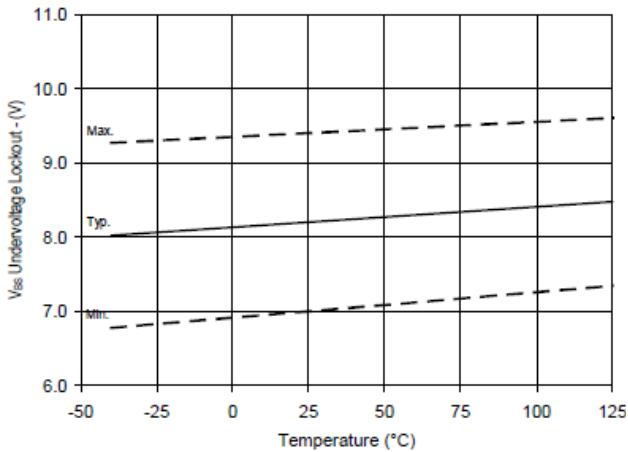
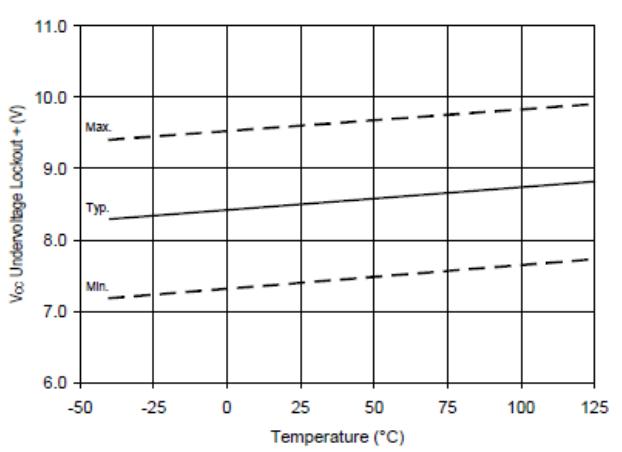
Figure 18B. Logic '1' Input Current vs. V_{DD} Voltage

Figure 19A. Logic '0' Input Current vs. Temperature

Figure 19B. Logic '0' Input Current vs. V_{DD} VoltageFigure 20. V_{BS} Undervoltage (+) vs. TemperatureFigure 21 V_{BS} Undervoltage (-) vs. TemperatureFigure 22. V_{CC} Undervoltage (+) vs. Temperature

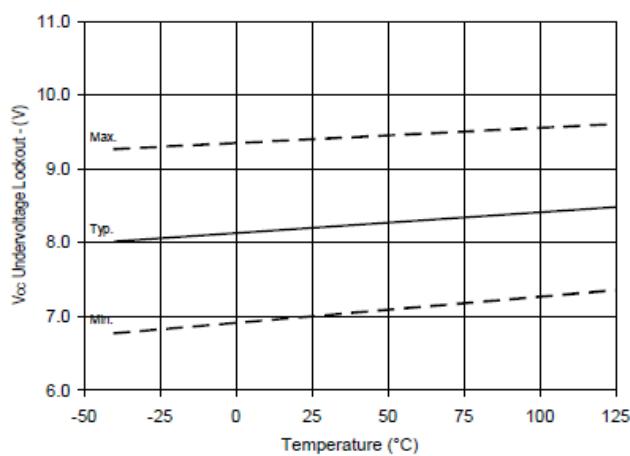
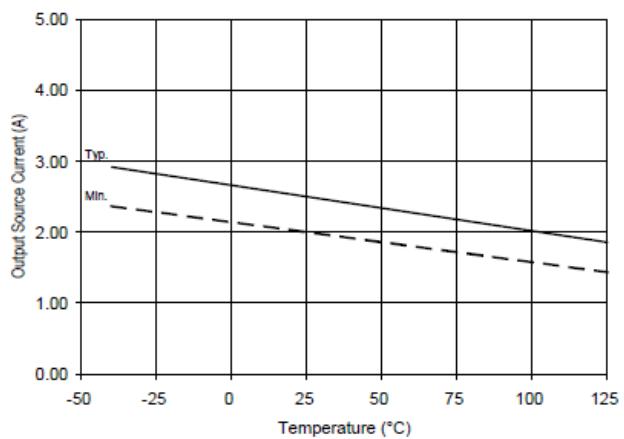
Figure 23. V_{CC} Undervoltage (-) vs. Temperature

Figure 24A. Output Source Current vs. Temperature

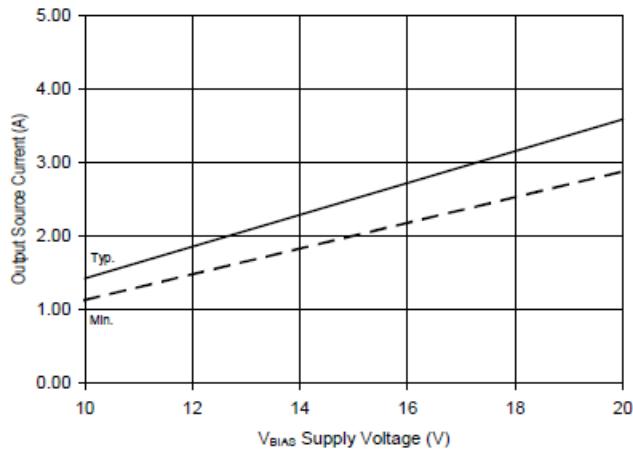


Figure 24B. Output Source Current vs. Voltage

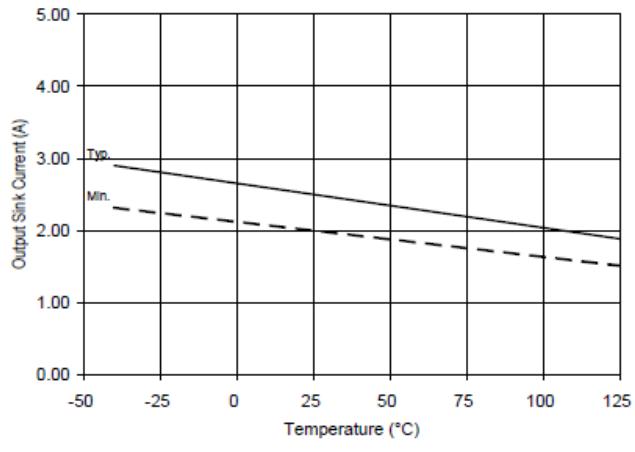


Figure 25A. Output Sink Current vs. Temperature

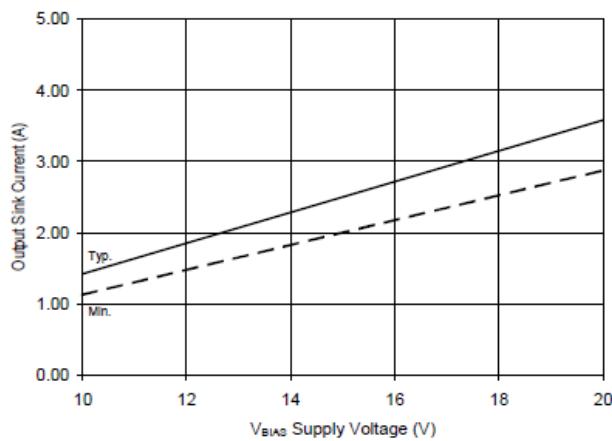
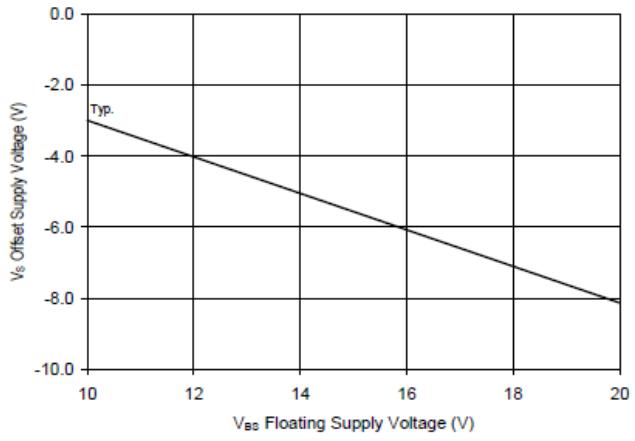


Figure 25B. Output Sink Current vs. Voltage

Figure 26. Maximum V_S Negative Offset vs. V_{BS} Supply Voltage

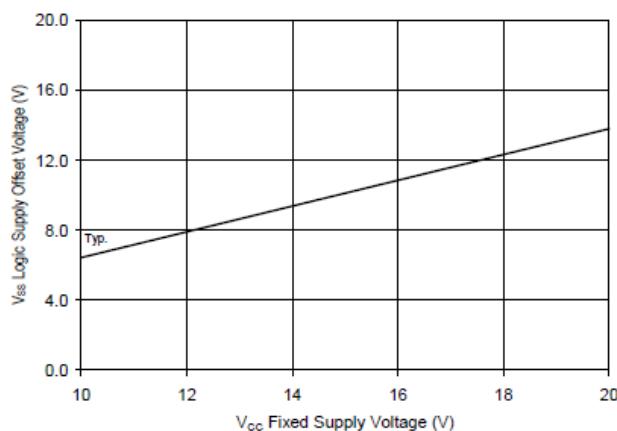
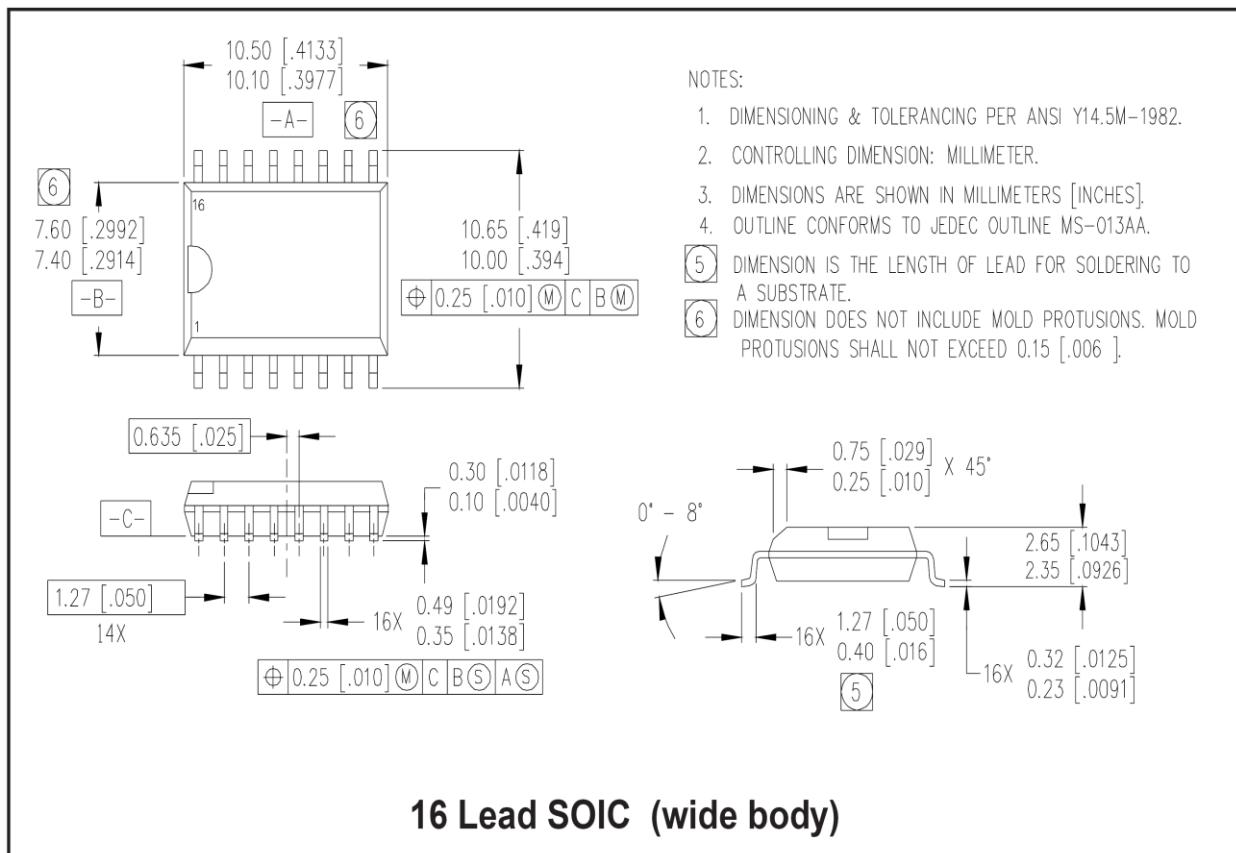
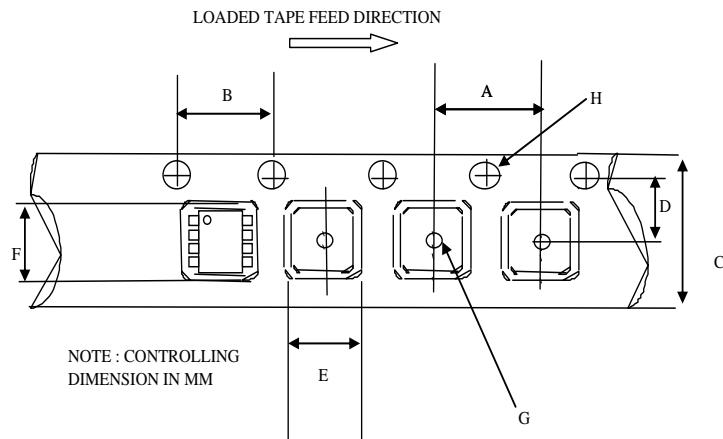


Figure 27. Maximum V_{ss} Positive Offset vs. V_{cc} Supply Voltage

Package Details

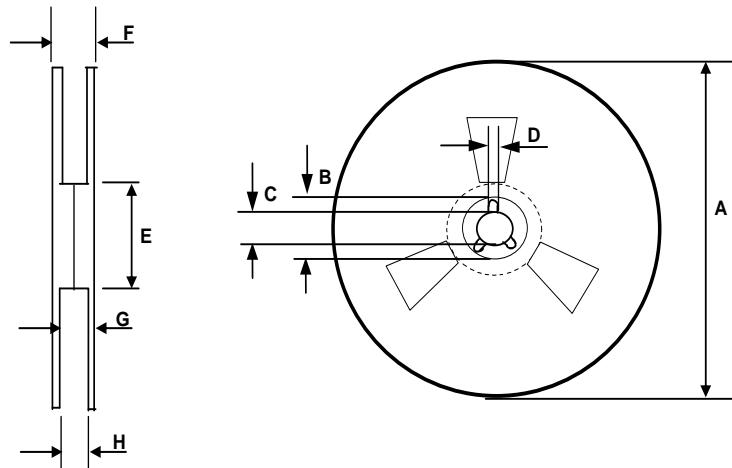


Tape and Reel Details



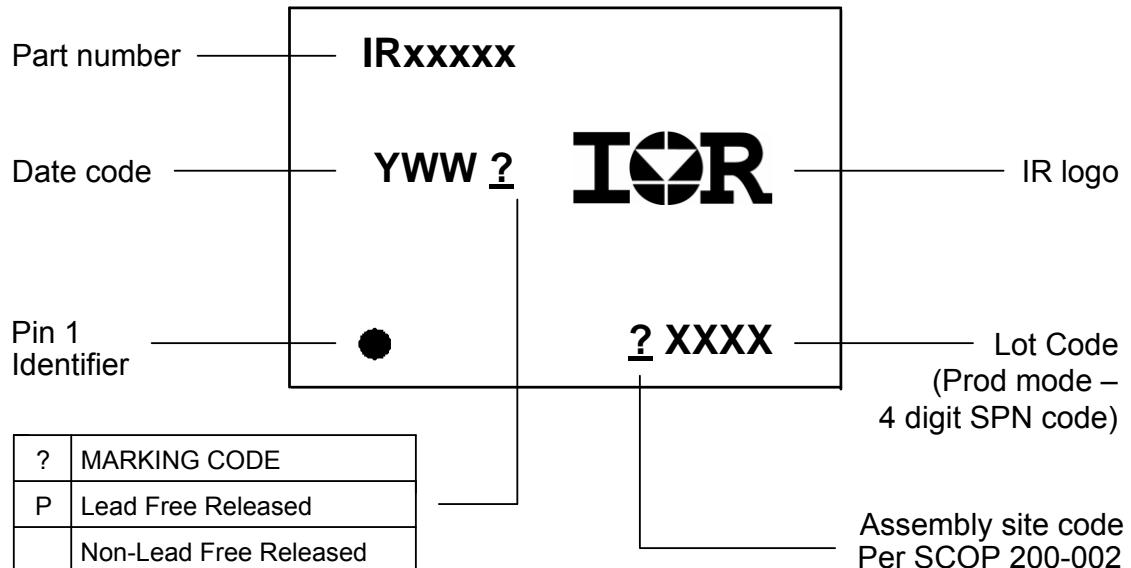
CARRIER TAPE DIMENSION FOR 16SOICN

Code	Metric		Imperial	
	Min	Max	Min	Max
A	7.90	8.10	0.311	0.318
B	3.90	4.10	0.153	0.161
C	15.70	16.30	0.618	0.641
D	7.40	7.60	0.291	0.299
E	6.40	6.60	0.252	0.260
F	10.20	10.40	0.402	0.409
G	1.50	n/a	0.059	n/a
H	1.50	1.60	0.059	0.062



REEL DIMENSIONS FOR 16SOICN

Code	Metric		Imperial	
	Min	Max	Min	Max
A	329.60	330.25	12.976	13.001
B	20.95	21.45	0.824	0.844
C	12.80	13.20	0.503	0.519
D	1.95	2.45	0.767	0.096
E	98.00	102.00	3.858	4.015
F	n/a	22.40	n/a	0.881
G	18.50	21.10	0.728	0.830
H	16.40	18.40	0.645	0.724

Part Marking Information

Qualification Information[†]

Qualification Level	Industrial ^{††} (per JEDEC JESD 47) Comments: This family of ICs has passed JEDEC's Industrial qualification. IR's Consumer qualification level is granted by extension of the higher Industrial level.
Moisture Sensitivity Level	MSL3 ^{†††} (per IPC/JEDEC J-STD-020)
RoHS Compliant	Yes

[†] Qualification standards can be found at International Rectifier's web site <http://www.irf.com/>

^{††} Higher qualification ratings may be available should the user have such requirements. Please contact your International Rectifier sales representative for further information.

^{†††} Higher MSL ratings may be available for the specific package types listed here. Please contact your International Rectifier sales representative for further information.

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For technical support, please contact IR's Technical Assistance Center
<http://www.irf.com/technical-info/>

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Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помошь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помошь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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